

STD100N3LF3

N-channel 30 V, 0.0045 Ω 80 A, DPAK planar STripFET™ II Power MOSFET

Features

Туре	v_{dSSS}	R _{DS(on)}	I _D	Pw
STD100N3LF3	30 V	<0.0055 Ω	80 A ⁽¹⁾	110 W

- 1. Current limited by package
- 100% avalanche tested
- Logic level threshold

Applications

- Switching application
 - Automotive

Description

This STripFET™ II Power MOSFET technology is among the latest improvements, which have been especially tailored to minimize on-state resistance providing superior switching performance.

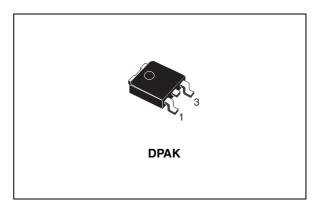


Figure 1. Internal schematic diagram

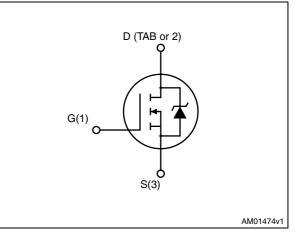


Table 1. Device summary

Order codes	Marking	Package	Packaging
STD100N3LF3	100N3LF3	DPAK	Tape and reel

Contents

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1 Electrical ratings

Table 2. Absolute maximum	ratings
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Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V _{GS} = 0)	30	V
V _{GS}	Gate-source voltage	± 20	V
I _D ⁽¹⁾	Drain current (continuous) at $T_C = 25 \ ^{\circ}C$	80	А
I _D	Drain current (continuous) at T _C =100 °C	70	А
I _{DM} ⁽²⁾	Drain current (pulsed)	320	А
P _{TOT}	Total dissipation at $T_C = 25 \ ^{\circ}C$	110	W
	Derating factor	0.73	W/°C
dv/dt ⁽³⁾	Peak diode recovery voltage slope	3.9	V/ns
T _{stg}	Storage temperature	-55 to 175	
TJ	Max. operating junction temperature		

1. Current limited by package.

2. Pulse width limited by safe operating area

3. $I_{SD} \leq 80A$, di/dt $\leq 360 A/\mu s$, $V_{DS} \leq V_{(BR)DSS}$, $T_J \leq T_{JMAX}$

Symbol	Parameter	Value	Unit
R _{thJC}	Thermal resistance junction-case max	1.36	°C/W
R _{thJA}	Thermal resistance junction-ambient max	100	°C/W
ТI	Maximum lead temperature for soldering purpose	275	°C

 Table 4.
 Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Not-repetitive avalanche current (pulse width limited by T _J max)	40	A
E _{AS}	Single pulsed avalanche energy (starting $T_J = 25$ °C, $I_D = I_{AV}$, $V_{DD} = 24$ V)	500	mJ



2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0$	30			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = Max rating, V _{DS} = Max rating @125 °C			1 10	μΑ μΑ
I _{GSS}	Gate body leakage current (V _{DS} = 0)	$V_{GS} = \pm 20 V$			±200	nA
V _{GS(th)}	Gate threshold voltage	V_{DS} = V_{GS} , I_D = 250 μ A	1		2.5	V
		$V_{GS} = 10 \text{ V}, I_D = 40 \text{ A}$ $V_{GS} = 5 \text{ V}, I_D = 20 \text{ A}$		0.0045 0.008	0.0055 0.01	Ω Ω
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 40 A @ 125 °C V _{GS} = 5 V,		0.0068		Ω
		I _D = 20 A @125 °C		0.0146		Ω

Table 5. On/off states

Table 6.	Dynamic
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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 _{fs} ⁽¹⁾	Forward transconductance	$V_{DS} = 10 V_{,} I_{D} = 15 A$	-	31		S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 25 V, f = 1 MHz, V _{GS} = 0	-	2060 728 67		pF pF pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 24 V, I_D = 80 A$ $V_{GS} = 5 V$ Figure 16 on page 9	-	20 7 7.5	27	nC nC nC
R _G	Gate input resistance	f = 1 MHz gate DC Bias = 0 test signal level = 20 mV open drain	-	1.9		Ω

1. Pulsed: pulse duration=300µs, duty cycle 1.5%



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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r t _{d(off)} t _f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 15 V, I_D = 40 A, R _G =4.7 Ω , V _{GS} =10 V Figure 15 on page 9	-	9 205 31 35	-	ns ns ns ns

Table 7. Switching times

Table 8.Source drain diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I _{SD}	Source-drain current		-		80	А
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		320	А
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 40 \text{ A}, V_{GS} = 0$	-		1.3	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I _{SD} = 80 A, di/dt = 100 A/μs, V _{DD} = 25 V, T _J = 150 °C <i>Figure 17 on page 9</i>	-	40 40 2		ns μC Α

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration=300µs, duty cycle 1.5%



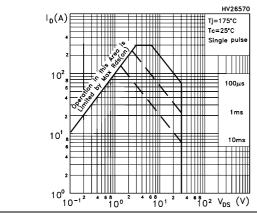
HV26605

8 V_{GS}(V)

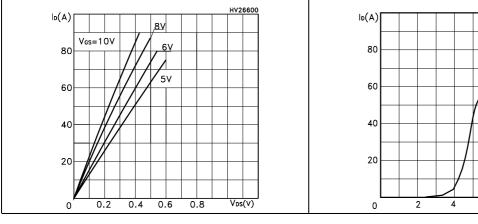
V_{Ds}=0.4V

2.1 Electrical characteristics (curves)

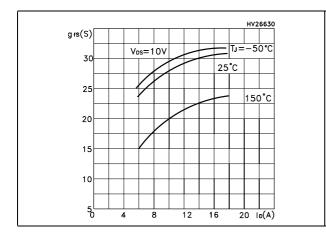
Figure 2. Safe operating area

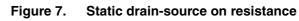


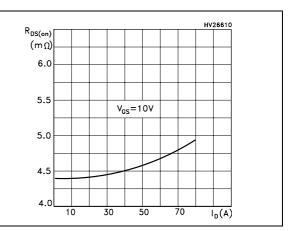












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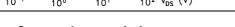
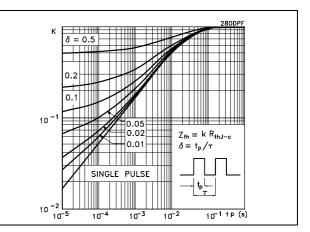


Figure 5. Transfer characteristics

Figure 3.



Thermal impedance

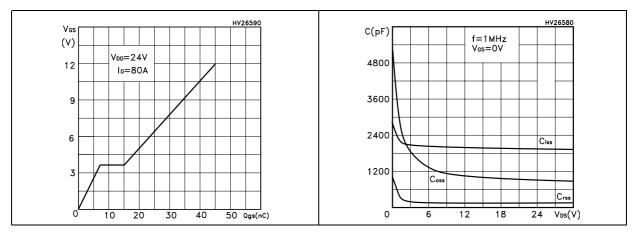


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

Figure 10. Normalized gate threshold voltage Figure 11. Normalized BV_{DSS} vs temperature vs temperature

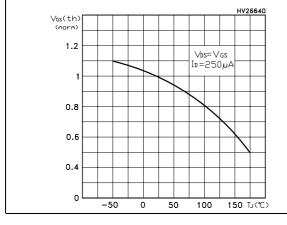


Figure 12. Normalized on resistance vs temperature

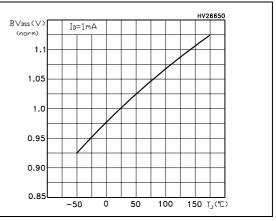


Figure 13. Source-drain diode forward characteristics

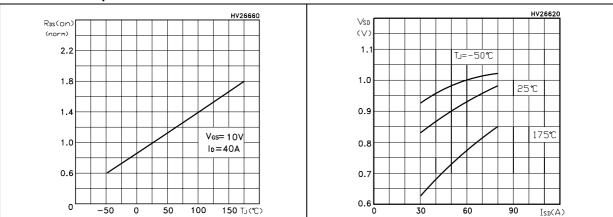
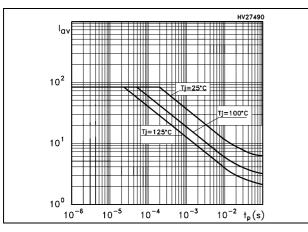


Figure 14. Allowable lav vs time in avalanche



The previous curve gives the single pulse safe operating area for unclamped inductive loads, under the following conditions:

P_{D(AVE)} = 0.5 * (1.3 * BV_{DSS} *I_{AV})

 $E_{AS(AR)} = P_{D(AVE)} * t_{AV}$

Where:

 ${\rm I}_{\rm AV}$ is the allowable current in avalanche

 $P_{D(AVE)}$ is the average power dissipation in avalanche (single pulse)

 t_{AV} is the time in avalanche



3 Test circuits

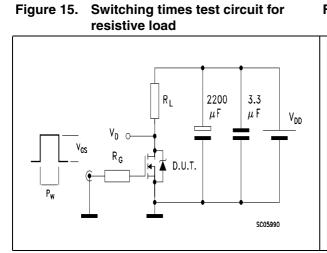
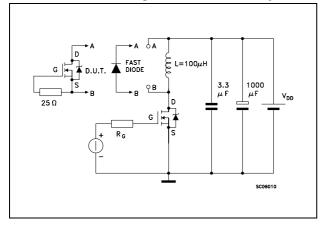


Figure 17. Test circuit for inductive load switching and diode recovery times



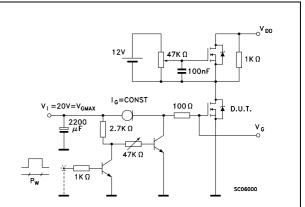


Figure 16. Gate charge test circuit



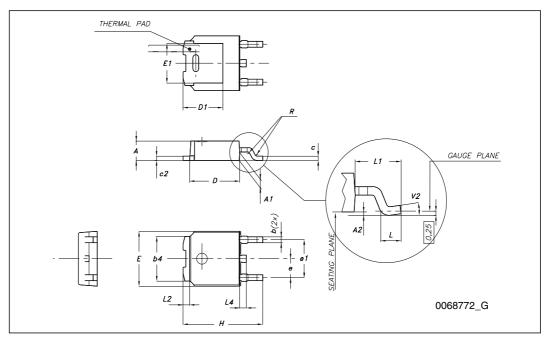
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



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TO-252 (DPAK) mechanical data						
DIM.	mm.					
	min.	typ	max.			
A	2.20		2.40			
A1	0.90		1.10			
A2	0.03		0.23			
b	0.64		0.90			
b4	5.20		5.40			
с	0.45		0.60			
c2	0.48		0.60			
D	6.00		6.20			
D1		5.10				
E	6.40		6.60			
E1		4.70				
е		2.28				
e1	4.40		4.60			
Н	9.35		10.10			
L	1					
L1		2.80				
L2		0.80				
L4	0.60		1			
R		0.20				
V2	0 °		8 °			

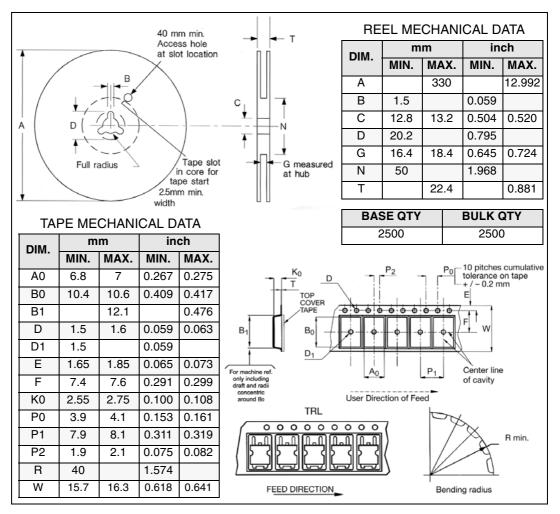




5 Packaging mechanical data



TAPE AND REEL SHIPMENT



6 Revision history

Table 9.Document revision history

Date	Revision	Changes
07-Feb-2006	1	Initial release.
07-May-2009	2	Added V _{GS(th)} max value in <i>Table 5: On/off states</i>
09-Nov-2009	3	Added V _{GS} parameter in <i>Table 2: Absolute maximum ratings</i>



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